

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8224180

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT	
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CORRECTIVE ASSIGNMENT TO CORRECT THE TITLE OF INVENTION ON ASSIGNMENT PREVIOUSLY RECORDED ON REEL 054542 FRAME 0873. previously recorded on Reel 054542 Frame 0873. Assignor(s) hereby confirms the ASSIGNMENT.	
RESUBMIT DOCUMENT ID:	508143236	
CONVEYING PARTY DATA		
	Name	Execution Date
	SATOSH I YONEDA	09/20/2023
	TETSUYA ENOMOTO	09/21/2023
RECEIVING PARTY DATA		
Name:	HD MICROSYSTEMS, LTD.	
Street Address:	4-25, KORAKU 1-CHOME BUNKYO-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	112-0004	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17043444
CORRESPONDENCE DATA		
Fax Number:	(312)577-7007	
	<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2024197000	
Email:	aschiavelli@fitcheven.com	
Correspondent Name:	ALAN E. SCHIAVELLI	
Address Line 1:	700 12TH STREET NW, SUITE 700	
Address Line 4:	WASHINGTON, D.C. 20005	
ATTORNEY DOCKET NUMBER:	20367 150085-US	
NAME OF SUBMITTER:	ALAN E. SCHIAVELLI	
SIGNATURE:	/Alan E. Schiavelli/	
DATE SIGNED:	10/17/2023	
Total Attachments: 5 source=Full page photo#page1.tif		

source=Full page photo#page2.tif
source=Full page photo#page3.tif
source=Full page photo#page4.tif
source=Full page photo#page5.tif

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6431918

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SATOSHI YONEDA	10/20/2020
TETSUYA ENOMOTO	10/21/2020
RECEIVING PARTY DATA	
Name:	HD MICROSYSTEMS, LTD.
Street Address:	4-25, KORAKU 1-CHOME
Internal Address:	BUNKYO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	112-0004
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17043444
CORRESPONDENCE DATA	
Fax Number:	(202)419-7007
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2024197000
Email:	aschiavelli@fitcheven.com
Correspondent Name:	ALAN E. SCHIAVELLI
Address Line 1:	1250 23RD STREET NW, SUITE 410
Address Line 4:	WASHINGTON, D.C. 20037-1164
ATTORNEY DOCKET NUMBER:	20367-150085-US
NAME OF SUBMITTER:	ALAN E. SCHIAVELLI
SIGNATURE:	/Alan E. Schiavelli/
DATE SIGNED:	12/04/2020
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4	
source=HIK-1702-PCT-US_Combined Declaration and Assignment#page1.tif	
source=HIK-1702-PCT-US_Combined Declaration and Assignment#page2.tif	
source=HIK-1702-PCT-US_Combined Declaration and Assignment#page3.tif	

PATENT

REEL: 065329 FRAME: 0666

Attorney Docket No.

**COMBINED DECLARATION FOR UTILITY OR DESIGN
PATENT APPLICATION AND ASSIGNMENT THEREOF**

As a below named inventor, I hereby declare that:

The below-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

METHOD FOR PRODUCING POLYIMIDE PRECURSOR, METHOD FOR PRODUCING PHOTSENSITIVE RESIN COMPOSITION, METHOD FOR PRODUCING PATTERN CURED PRODUCT, METHOD FOR PRODUCING INTERLAYER INSULATING FILM, COVER COAT LAYER OR SURFACE PROTECTIVE FILM, AND METHOD FOR PRODUCING ELECTRONIC COMPONENT

(Title of Invention)

the specification of which:

- is attached hereto, or
- was filed by an authorized person on my behalf on April 3, 2018, as United States Application Number or PCT International Application Number PCT/JP2018/014273, and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, including, for continuation-in-part applications, material information which became available between the filing date of the prior application and the filing date of the continuation-in-part application.

Attorney Docket No.

I, for good and valuable consideration, receipt of which is hereby acknowledged, have assigned and do hereby assign and sell, which confirms any previous assignment by me or by operation of law, to **HD MicroSystems, Ltd.**, a Japanese corporation, having its principal place of business at 4-25, Koraku 1-chome, Bunkyo-ku, Tokyo 112-0004 Japan ("Assignee"), its successors, assigns, and legal representatives, the entire right, title, and interest, in and to all subject matter and improvements invented, made, or conceived by me and described in the application for patent identified above and in and to all patent and all patent convention and treaty rights of all kinds, including the right to claim priority from said application, and all rights in and to any utility model, continuation, continuation-in-part, and divisional application therefrom, and any reissue or re-examination as to any patent issuing therefrom, in all countries throughout the world, for all such subject matter described therein, including all rights of action and rights to recover damages for past infringements.

I agree that on request and without further consideration, I will communicate to the Assignee or its representatives or nominees any facts known to me respecting the inventions and improvements and testify in any legal proceeding, make all rightful oaths, sign all lawful papers, and execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights in all countries including, but not limited to, any provisional, non-provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, for any derivation proceedings relating thereto, and, as to any patents that issue from such applications, for any supplemental examination, derivation proceeding, opposition, post grant review, reissue, re-examination, *inter partes* review, or extension thereof, and generally do everything possible to aid the Assignee, its successors, assigns, and nominees to obtain and enforce proper patent protection for the invention and its improvements in all countries.

I hereby authorize and request the attorneys of Fitch, Even, Tabin & Flannery, LLP to insert above the filing date and application number of said application when known.

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made herein on information and belief are believed to be true.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Attorney Docket No.

Legal Name of Inventor:
(Given names first, with Family name last)

Satoshi YONEDA

Inventor's Signature:

DocuSigned by:

/Satoshi/ /Yoneda/

259734345B41439...

Date:

9/20/2023

Inventor's Address:

c/o Hitachi Chemical DuPont MicroSystems,
Ltd., 13-1, Higashi-cho 4-chome, Hitachi-shi,
Ibaraki 317-8555 JAPAN

Attorney Docket No.

Legal Name of Inventor:
(Given names first, with Family name last)

Tetsuya ENOMOTO

Inventor's Signature:

DocuSigned by:
/Tetsuya Enomoto/
E051894C9D9B4E2

Date:

9/21/2023

Inventor's Address:

c/o Hitachi Chemical DuPont MicroSystems,
Ltd., 13-1, Higashi-cho 4-chome, Hitachi-shi,
Ibaraki 317-8555 JAPAN